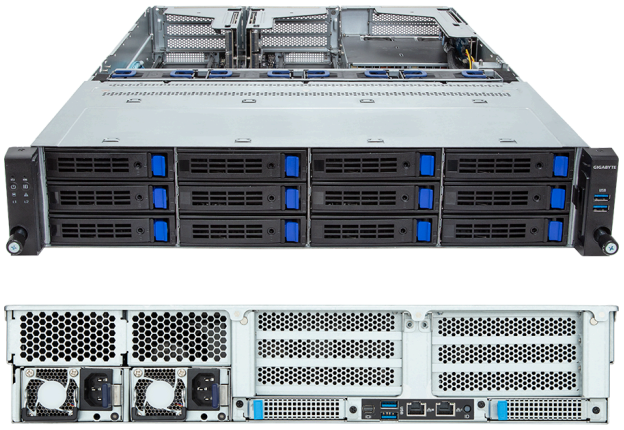
GIGABYTE™

R263-S30-AAC2

Rack Server - 5th/4th Gen Intel® Xeon® Scalable - 2U UP 12-Bay SATA/SAS Platinum



Key Features

- Single 5th/4th Gen Intel® Xeon® Scalable Processors
- Single Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- 1 x 1 Gb/s LAN port via Intel® I210-AT
- 12 x 3.5"/2.5" SATA/SAS hot-swap bays
- 1 x M.2 PCIe Gen3 x4
- 4 x FHHL PCIe Gen5 x16 and x8
- 2 x OCP NIC 3.0 PCIe Gen5 x16
- 1+1 1300 W 80 PLUS Platinum redundant power supplies

Applications

Networks Server, Servers for Hybrid/Private Cloud...

Specification

Dimensions	2U (W438 x H87.5 x D710 mm)
Motherboard	MS33-DC0
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Single processor, TDP up to 350 W
OS Compatibility	OS Support List
Socket	1 x LGA 4677 (Socket E)
Chipset	Intel® C741
Memory	8-Channel DDR5 RDIMM, 16 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC) [4th Gen Intel Xeon] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC) [Intel Xeon Max Series] Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC)
LAN	1 x 1 Gb/s LAN (1 x Intel® I210-AT), Support NCSI 1 x 10/100/1000 Mb/s Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	**Front hot-swap:** 12 x 3.5"/2.5" SATA/**SAS** [1] **Internal M.2:** 1 x M.2 (2280/22110), PCIe Gen3 x4 [1] SAS card is required to support SAS drives.
RAID	Intel® SATA RAID 0/1/10/5 Onboard VROC key header Support **optional** RAID add-in cards
PCIe Expansion Slots	2 x FHHL PCIe Gen5 x16 2 x FHHL PCIe Gen5 x8 2 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
I/O Ports	**Front:** 2 x USB 3.2 Gen1 **Rear:** 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
Backplane Board	PCIe Gen4 x4 or SATA 6 Gb/s or SAS 12 Gb/s
TPM	1 x TPM header (SPI), Optional TPM 2.0 kit: CTM010
Power Supply	1+1 1300 W 80 PLUS Platinum redundant power supplies AC Input: 100-240 V
System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
System Fans	4 x 80x80x38mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x R263-S30-AAC2 1 x CPU heatsink 1 x Mini-DP to D-Sub cable 3 x Carriers 1 x 2-Section Rail kit
Ordering Part Numbers	6NR263S30DR000ABC2*
Optional Parts	- 3-Section Rail kit (Supports CMA): 25HB2-A56120-K0R - Cable Management Arm: 25HBZ-R18100-K0R

Learn more at: https://www.gigabyte.com/Enterprise

* All specifications are subject to change without notice. Please visit our website for the latest information.
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